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ESJ-Series H-Pin Socket

Accelerated life testing solution

ESJ-Series socket is a high-performance burn-in socket, with dual latch clamshell lid to provide co-planar pressure on the DUT when the lid is actuated.

The patented H-Pin contact technology in the ESJ-Series socket provides versatility and the ability to use the same socket for multiple application needs and test functions.

Option for heatsink addresses the wide variety of product requirements targeted specifically for advanced mobile SoC, CPU, GPU, or other IoT application devices. When consistent reliability is required, ESJ Series is the product trusted in the industry.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

Benefits

- Configurable design, in-house tooling, molding and machining provide short lead times.
- Extensive catalog of components, drive reduction in cost of test.
- Modular lid design allows for easy configuration of different end-use requirements.
- Exceptional electrical performance provides wide RF bandwidth.

Feature Options

- Spring loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Max component clearance under the DUT
- High temperature materials for above 200 °C application

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ESJ Series socket specifications

Mechanical properties

- **Pitch**: ≥0.30 mm
- **Package size**:
  LGA: 10 mm to 31 mm
  BGA: 10 mm to 31 mm
- **Pin count**: 3000
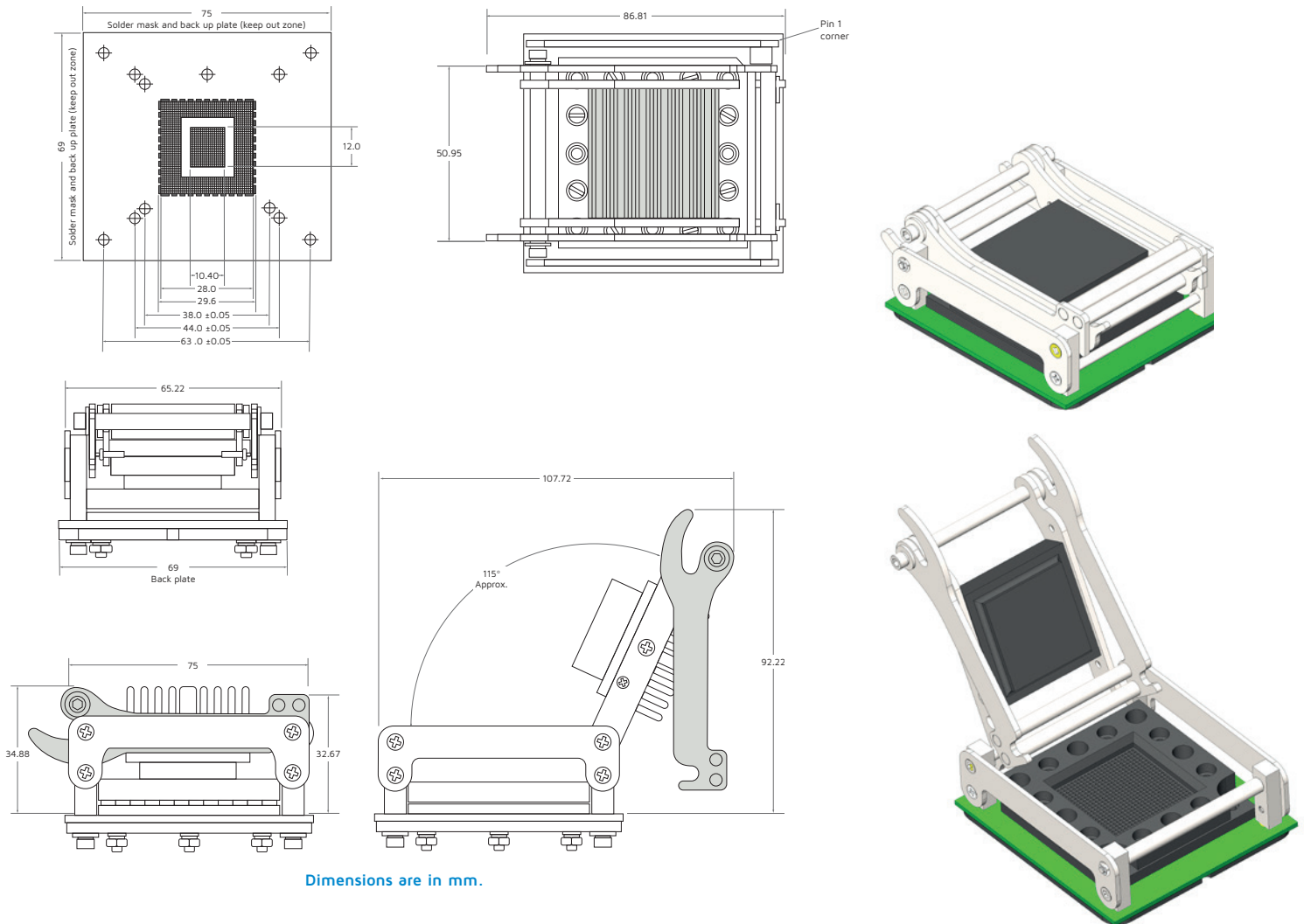- **Temperature**: −55 °C to 260 °C

Electrical properties

- **Contact resistance**: 35 mΩ
- **Current carrying capacity**: up to 4 A

Materials

- **Contact**: BeCu/Au plated
- **Spring**: SS/Au plated
- **Socket**: Engineering plastics

ESJ Series socket dimensions

Dimensions are in mm.